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List of Publications

- 1) Dheeraj Jaiswal, Dileep Pathote, Vikrant Singh, C.K Behera, Electrochemical behavior of lead-free Sn-0.7Cu-xIn solders alloys in 3.5 wt.% NaCl solution. (Journal of Materials Science Materials in Electronics, September 2021 ,<https://link.springer.com/article/10.1007%2Fs10854-021-06824-3>)
- 2) Dheeraj Jaiswal, Dileep Pathote, Vikrant Singh, C.K Behera, Effect of Al addition on Electrochemical behavior of Sn-0.7Cu-xAl lead-free solders alloys in 3.5 wt. % NaCl solution. (Journal Of Materials Engineering and Performance, March 2022, 10.1007/s11665-022-06771-y)
- 3) Dheeraj Jaiswal, Sharvan Kumar, C.K Behera, Electrochemical behavior of Sn-9Zn-xCu solder alloy in 3.5wt. % NaCl solution at room temperature (Material Today Communication, revision)
- 4) Dheeraj Jaiswal, Dileep Pathote, Vikrant Singh, C.K Behera, Electrochemical behavior of lead-free Sn-In-Al solders alloys in 3.5 wt.% NaCl solution (Materials Today : Proceeding February 2022,<http://dx.doi.org/10.1016/j.matpr.2022.02.315>)